



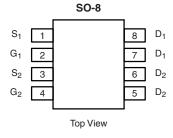
Dual N-Channel 2.5-V (G-S) MOSFET

| PRODUCT SUMMARY | | | | |
|---------------------|----------------------------------|--------------------|--|--|
| V _{DS} (V) | $R_{DS(on)}\left(\Omega\right)$ | I _D (A) | | |
| 20 - | 0.020 at V _{GS} = 4.5 V | 8.2 | | |
| | 0.030 at V _{GS} = 2.5 V | 6.7 | | |

FEATURES

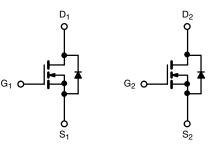
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFETS
- Compliant to RoHS Directive 2002/95/EC





Ordering Information: Si9926BDY-T1-E3 (Lead (Pb)-free)

Si9926BDY-T1-GE3 (Lead (Pb)-free and Halogen-free)



N-Channel MOSFET

N-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS $T_A = 25 ^{\circ}C$, unless otherwise noted | | | | | | |
|--|------------------------|-----------------------------------|-------------|--------------|------|--|
| Parameter | | Symbol | 10 s | Steady State | Unit | |
| Drain-Source Voltage | | V _{DS} | 20 | | V | |
| Gate-Source Voltage | | V _{GS} | ± 12 | | | |
| Continuous Dunin Comment /T 450 00\8 | T _A = 25 °C | I _D | 8.2 | 6.2 | | |
| Continuous Drain Current (T _J = 150 °C) ^a | T _A = 70 °C | | 6.5 | 4.9 | | |
| Pulsed Drain Current | | I _{DM} | 30 | | Α | |
| Continuous Source Current (Diode Conduction) ^a | | I _S | 1.7 | 0.95 | l | |
| M | T _A = 25 °C | P _D | 2.0 | 1.14 | W | |
| Maximum Power Dissipation ^a | T _A = 70 °C | | 1.3 | 0.72 | | |
| Operating Junction and Storage Temperature Range | | T _J , T _{stg} | - 55 to 150 | | °C | |

| THERMAL RESISTANCE RATINGS | | | | | |
|--|--------------|---------------------|---------|---------|------|
| Parameter | | Symbol | Typical | Maximum | Unit |
| Manifestore bounding to Aughing 18 | t ≤ 10 s | - R _{thJA} | 52 | 62.5 | °C/W |
| Maximum Junction-to-Ambient ^a | Steady State | | 90 | 110 | |
| Maximum Junction-to-Foot (Drain) | Steady State | R_{thJF} | 32 | 40 | |

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

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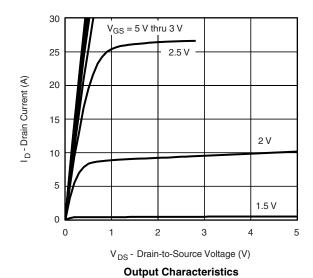
| SPECIFICATIONS T _J = 25 °C, unless otherwise noted | | | | | | | | |
|--|---------------------|---|---|-------------|-------|------|--|--|
| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit | | |
| Static | | | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$ | 0.6 | | 1.5 | V | | |
| Gate-Body Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$ | | | ± 100 | nA | | |
| Zero Gate Voltage Drain Current | I _{DSS} | $V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$ | _S = 20 V, V _{GS} = 0 V | | 1 | μΑ | | |
| Zero Gate voltage Drain Current | | V _{DS} = 20 V, V _{GS} = 0 V, T _J = 55 °C | | | 5 | | | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$ | 30 | | | Α | | |
| Durin Course Co Olata Basistana a | B | $V_{GS} = 4.5 \text{ V}, I_D = 8.2 \text{ A}$ | | 0.016 0.020 | | Ω | | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | $V_{GS} = 2.5 \text{ V}, I_D = 3.3 \text{ A}$ | $V_{GS} = 2.5 \text{ V}, I_D = 3.3 \text{ A}$ | | 0.030 | | | |
| Forward Transconductance ^a | 9 _{fs} | $V_{DS} = 15 \text{ V}, I_D = 8.2 \text{ A}$ | | 29 | | S | | |
| Diode Forward Voltage ^a | V_{SD} | I _S = 1.7 A, V _{GS} = 0 V | | 0.8 | 1.2 | V | | |
| Dynamic ^b | | | | | | | | |
| Total Gate Charge | Q_g | | | 11 | 20 | | | |
| Gate-Source Charge | Q_{gs} | Q_{gs} $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 8.2 \text{ A}$ | | 2.5 | | nC | | |
| Gate-Drain Charge | Q_{gd} | | | 3.2 | | | | |
| Turn-On Delay Time | t _{d(on)} | | | 35 | 55 | | | |
| Rise Time | t _r | $V_{DD} = 10 \text{ V}, R_L = 10 \Omega$ | | 50 | 75 | | | |
| Turn-Off Delay Time | t _{d(off)} | $I_{D}\cong$ 1 A, V_{GEN} = 4.5 V, R_{g} = 6 Ω | | 31 | 50 | ns | | |
| Fall Time | t _f | | | 15 | 25 | | | |
| Source-Drain Reverse Recovery Time | t _{rr} | $I_F = 1.7 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}$ | | 30 | 60 | | | |

Notes:

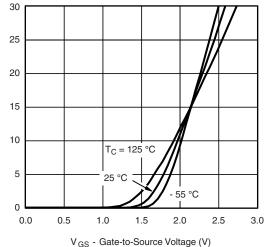
- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





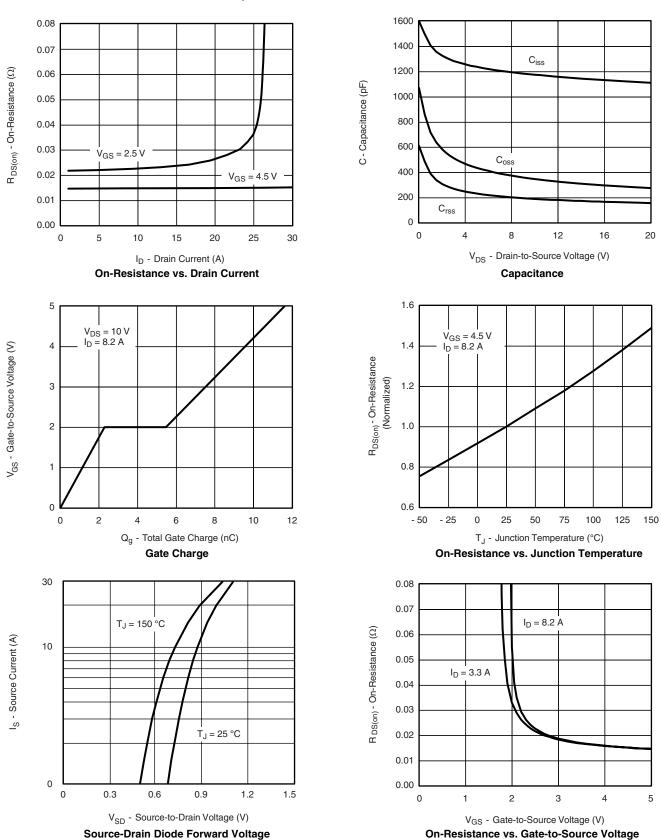


Transfer Characteristics





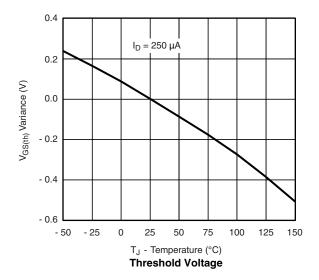
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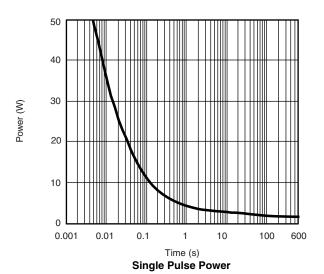


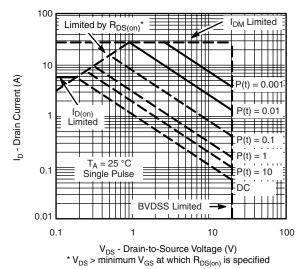
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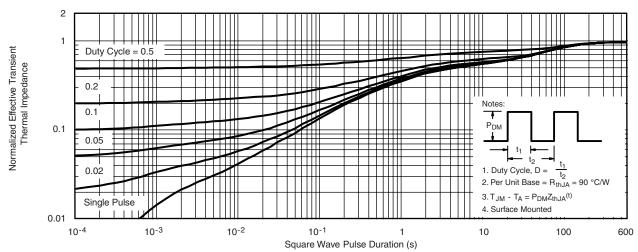
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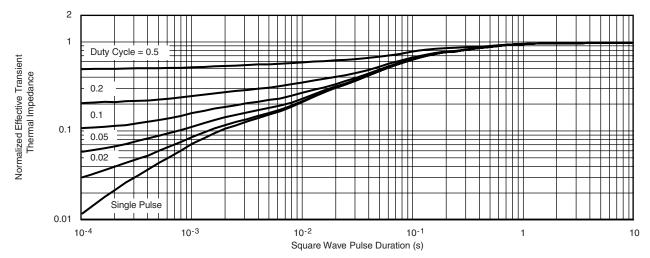
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Foot

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